

Jieshi Chen

List of Publications by Year in descending order

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28
papers

450
citations

687363

13
h-index

752698

20
g-index

29
all docs

29
docs citations

29
times ranked

249
citing authors

#	ARTICLE	IF	CITATIONS
1	Effects of doping trace Ni element on interfacial behavior of Sn/Ni (polycrystal/single-crystal) joints. Soldering and Surface Mount Technology, 2022, 34, 124-133.	1.5	38
2	Structural stability, elasticity, thermodynamics, and electronic structures of L12-type Ni ₃ X (X=Al, Ti, V). Tj ETQq0 0,0 rgBT /Ov	1.8	2
3	Effects of solder thickness on interface behavior and nanoindentation characteristics in Cu/Sn/Cu microbumps. Welding in the World, Le Soudage Dans Le Monde, 2022, 66, 973-983.	2.5	46
4	Effect of boron on the structural stability, mechanical properties, and electronic structures of β -Ni ₃ Al in TLP joints of nickel-based single-crystal alloys. Materials Today Communications, 2022, 31, 103375.	1.9	22
5	Forming mechanism and growth of Kirkendall voids of Sn/Cu joints for electronic packaging: A recent review. Journal of Advanced Joining Processes, 2022, 6, 100125.	2.7	16
6	Effects of the beam offset on microstructure and properties of electron beam welded tantalum and Inconel 718 joints. Materials Research Express, 2021, 8, 046537.	1.6	0
7	Microstructure and mechanical properties of rhenium and GH3128 superalloy dissimilar welded joints by electron beam welding. Materials Research Express, 2021, 8, 056512.	1.6	4
8	Effect of solution treatment on the microstructure of dissimilar welding joints of Ta-10W and GH3128. Materials Research Express, 2021, 8, 066527.	1.6	2
9	A review on the effect of laser pulse shaping on the microstructure and hot cracking behavior in the welding of alloys. Optics and Laser Technology, 2021, 140, 107094.	4.6	28
10	Electronic and mechanical properties of monocrystalline silicon doped with trace content of N or P: A first-principles study. Solid State Sciences, 2021, 120, 106723.	3.2	19
11	Phase stability, elasticity, hardness and electronic structures for binary M _n B _m (M=Al, Ni). Tj ETQq1 1 0.784314 rgB Phase Transitions, 2020, 93, 158-174.	1.3	13
12	Effect of crystal structure of nickel substrates on interfacial behaviors in Sn/Ni soldered joints. Materials Letters, 2020, 278, 128424.	2.6	6
13	Interfacial transfer and phase evolution between Cu and Sn solder doped with minor Cu, Ag and Ni: experimental and theoretical investigations. Applied Physics A: Materials Science and Processing, 2020, 126, 1.	2.3	12
14	Phase stability, brittle-ductile transition, and electronic structures of the TiAl alloying with Fe, Ru, Ge, and Sn: a first-principle investigation. Journal of Molecular Modeling, 2020, 26, 320.	1.8	6
15	Systematically investigate mechanical and electrical properties of Bi ₂ O ₂ Se by Te atom substitution and compare it with homologue Bi ₂ O ₂ Te from first-principles calculations. Materials Today Communications, 2020, 24, 101182.	1.9	9
16	Forming Limit Evaluation for AA5182 Aluminum Alloy at Warm Temperatures Based on M $\dot{\epsilon}$ -K Model. Journal of Materials Engineering and Performance, 2020, 29, 1176-1184.	2.5	5
17	The Zn accumulation behavior, phase evolution and void formation in Sn-xZn/Cu systems by considering trace Zn: a combined experimental and theoretical study. Journal of Materials Research and Technology, 2019, 8, 4141-4150.	5.8	43
18	Weld penetration in situ prediction from keyhole dynamic behavior under time-varying VPPAW pools via the OS-ELM model. International Journal of Advanced Manufacturing Technology, 2019, 104, 3929-3941.	3.0	15

#	ARTICLE	IF	CITATIONS
19	Effects of Co dopant on the mechanical and magnetic properties of Cr ₂₃ C ₆ by using first principles calculation. <i>Journal of Alloys and Compounds</i> , 2019, 804, 538-548.	5.5	6
20	Effect of substrates on the formation of Kirkendall voids in Sn/Cu joints. <i>Welding in the World, Le Soudage Dans Le Monde</i> , 2019, 63, 751-757.	2.5	23
21	A new method to reliably determine elastic strain of various crystal structures from atomic-resolution images. <i>Scientific Reports</i> , 2019, 9, 16399.	3.3	3
22	Interface Growth and Void Formation in Sn/Cu and Sn _{0.7} Cu/Cu Systems. <i>Applied Sciences (Switzerland)</i> , 2018, 8, 2703.	2.5	13
23	Diode Laser Welding/Brazing of Aluminum Alloy to Steel Using a Nickel Coating. <i>Applied Sciences (Switzerland)</i> , 2018, 8, 922.	2.5	19
24	Optimization of hot stamping cooling system using segmented model. <i>International Journal of Advanced Manufacturing Technology</i> , 2017, 93, 1357-1365.	3.0	26
25	Multi-scale simulation of nanoindentation on cast Inconel 718 and NbC precipitate for mechanical properties prediction. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2016, 662, 385-394.	5.6	21
26	Study of curvature and pre-damage effects on the edge stretchability of advanced high strength steel based on a new simulation model. <i>International Journal of Material Forming</i> , 2016, 9, 269-276.	2.0	12
27	Effects of additive elements on structural and electronic properties of Sn-based intermetallics by first principles. <i>Materials Research Express</i> , 2014, 1, 025702.	1.6	10
28	Fracture Morphologies of Advanced High Strength Steel During Deformation. <i>Acta Metallurgica Sinica (English Letters)</i> , 2014, 27, 101-106.	2.9	31